Title (en)

METHOD AND DEVICE FOR SECURE, INSULATED AND ELECTRICALLY CONDUCTIVE ASSEMBLING OF TREATED SEMICONDUCTOR WAFERS

Title (de)

FESTES ISOLIERENDES UND ELEKTRISCH LEITENDES VERBINDEN PROZESSIERTER HALBLEITERSCHEIBEN

Title (fr)

PROCEDE ET DISPOSITIF POUR ASSEMBLER SOLIDEMENT, DE MANIERE ISOLANTE ET ELECTROCONDUCTRICE, DES PLAQUETTES DE SEMICONDUCTEURS TRAITEES

Publication

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Application

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Abstract (en)

[origin: WO2005042401A1] The invention concerns a method and a device for assembling treated semiconductor wafers (1, 2), for obtaining not only a secure assembly, but an electrical connection (5) between the semiconductor wafers or between the electronic structures (3) comprising the latter as well. The invention is characterized in that the secure assembly is produced by means of structured intermediate glass layers (6; 6a), with low melting point, acting as insulating layers, and the electrical connection is produced by means of an electroconductive sealing glass (5).

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